



SSC8L620GT8

N-Channel Enhancement Mode MOSFET

➤ Features

| V_{DS} | V_{GS} | $R_{DS(ON)}$ Typ. | I_D |
|----------|-----------|---------------------|-------|
| 60V | $\pm 20V$ | 3.9m Ω @10V | 134A |
| | | 4.9m Ω @4.5V | |

➤ Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

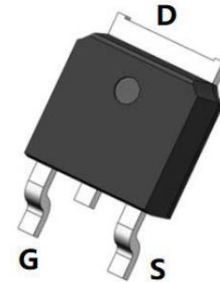
➤ Applications

- Intelligent Lighting
- Load Switch
- Portable Devices
- DCDC Conversion

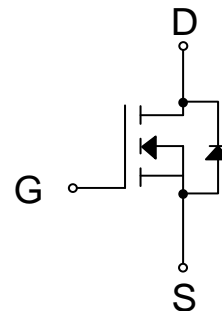
➤ Ordering Information

| Device | Package | Shipping |
|-------------|-----------|-----------|
| SSC8L620GT8 | TO-252-2L | 2500/Reel |

➤ Pin configuration



TO-252-2L(Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

| Symbol | Parameter | Ratings | Unit |
|-----------|--|---------------------------|--------------------|
| V_{DSS} | Drain-to-Source Voltage | 60 | V |
| V_{GSS} | Gate-to-Source Voltage | ± 20 | V |
| I_D | Continuous Drain Current ^d | $T_C=25^{\circ}\text{C}$ | A |
| | | $T_C=100^{\circ}\text{C}$ | |
| I_{DSM} | Continuous Drain Current ^a | $T_A=25^{\circ}\text{C}$ | A |
| | | $T_A=70^{\circ}\text{C}$ | |
| I_{DM} | Pulsed Drain Current ^b | 536 | A |
| P_D | Power Dissipation ^c | $T_C=25^{\circ}\text{C}$ | W |
| | | $T_C=100^{\circ}\text{C}$ | |
| P_{DSM} | Power Dissipation ^a | $T_A=25^{\circ}\text{C}$ | W |
| | | $T_A=70^{\circ}\text{C}$ | |
| I_{AS} | Avalanche Current ^b $L=0.5\text{mH}$ Single Pulse | 30 | A |
| E_{AS} | Avalanche Energy ^b $L=0.5\text{mH}$ Single Pulse | 225 | mJ |
| T_J | Operation junction temperature | -55~150 | $^{\circ}\text{C}$ |
| T_{STG} | Storage temperature range | -55~150 | |

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

| Symbol | Parameter | Ratings | Max. | Unit |
|-----------------|---|---------|------|-----------------------------|
| $R_{\theta JA}$ | Junction-to-Ambient Thermal Resistance ^a | 38 | 50 | $^{\circ}\text{C}/\text{W}$ |
| $R_{\theta JC}$ | Junction-to-Case Thermal Resistance | 1.1 | 2 | |

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.



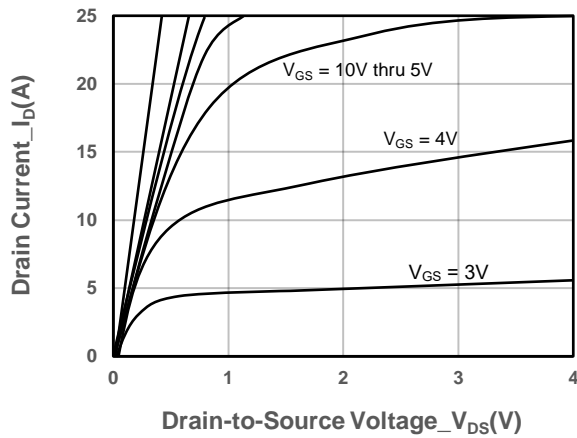
SSC8L620GT8

➤ Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

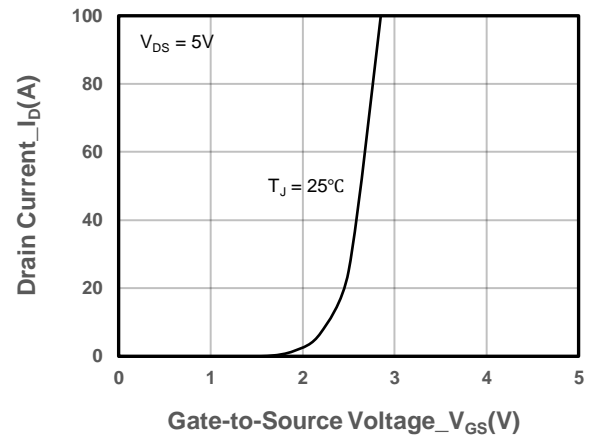
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------------------|---------------|---|------|------|-----------|------------|
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = 250\mu A$ | 60 | | | V |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$ | 1.0 | 1.6 | 2.4 | V |
| Drain-Source On-Resistance | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 20A$ | | 3.9 | 5.0 | m Ω |
| | | $V_{GS} = 4.5V, I_D = 10A$ | | 4.9 | 6.4 | |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 60V, V_{GS} = 0V$ | | | 1 | μA |
| Gate-Source Leak Current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | | ± 100 | nA |
| Transconductance | G_{FS} | $V_{DS} = 5V, I_D = 10A$ | | 36 | | S |
| Forward Voltage | V_{SD} | $V_{GS} = 0V, I_S = 10A$ | | 0.8 | 1.3 | V |
| Gate Resistance | R_G | $V_{DS} = 0V, f = 1MHz$ | | 0.6 | | Ω |
| Input Capacitance | C_{ISS} | $V_{DS} = 30V, V_{GS} = 0V,$ $f = 1MHz$ | | 2770 | | pF |
| Output Capacitance | C_{OSS} | | | 815 | | |
| Reverse Transfer Capacitance | C_{RSS} | | | 25 | | |
| Total Gate Charge | Q_G | $V_{GS} = 10V, V_{DS} = 30V,$ $I_D = 20A$ | | 48.7 | | nC |
| Gate to Source Charge | Q_{GS} | | | 8.1 | | |
| Gate to Drain Charge | Q_{GD} | | | 8.2 | | |
| Turn-on Delay Time | $T_{D(ON)}$ | $V_{GS} = 10V, V_{DS} = 30V,$ $I_D = 20A, R_G = 3\Omega$ | | 9.6 | | ns |
| Rise Time | T_r | | | 17.2 | | |
| Turn-off Delay Time | $T_{D(OFF)}$ | | | 38.4 | | |
| Fall Time | T_f | | | 22.3 | | |
| Diode Recovery Time | T_{rr} | $I_F = 20A, di/dt = 500A/\mu s$ | | 196 | | ns |
| Diode Recovery Charge | Q_{rr} | $I_F = 20A, di/dt = 500A/\mu s$ | | 635 | | nC |



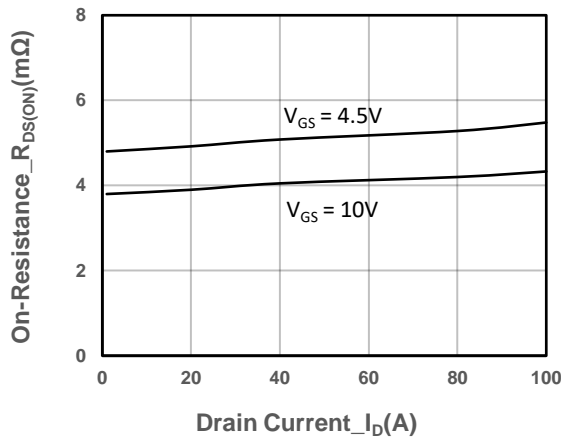
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



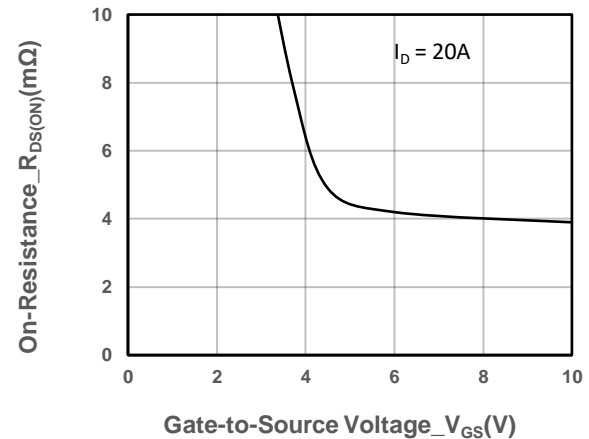
Output Characteristics



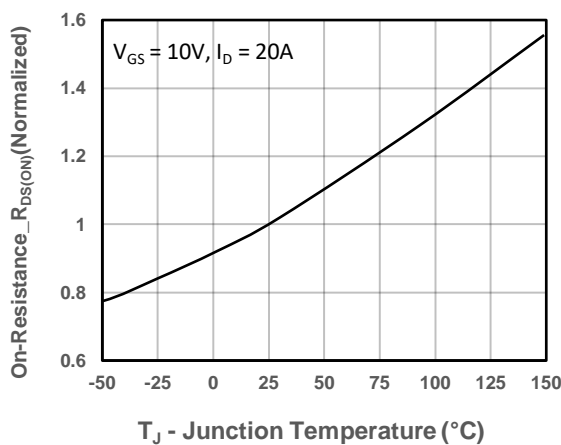
Transfer Characteristics



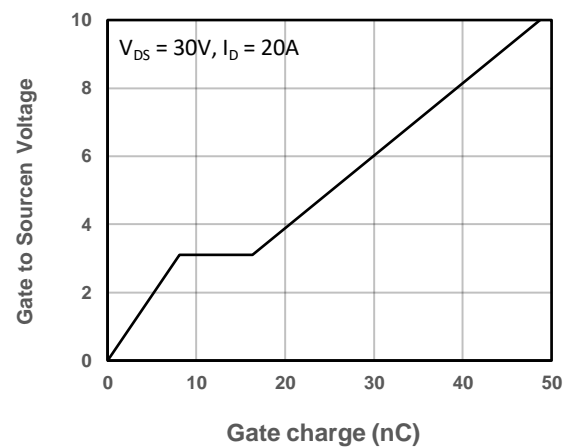
On-Resistance vs. Drain Current and Gate Voltage



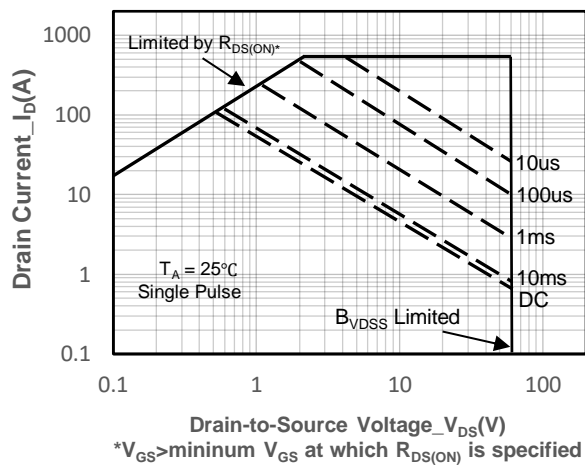
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature

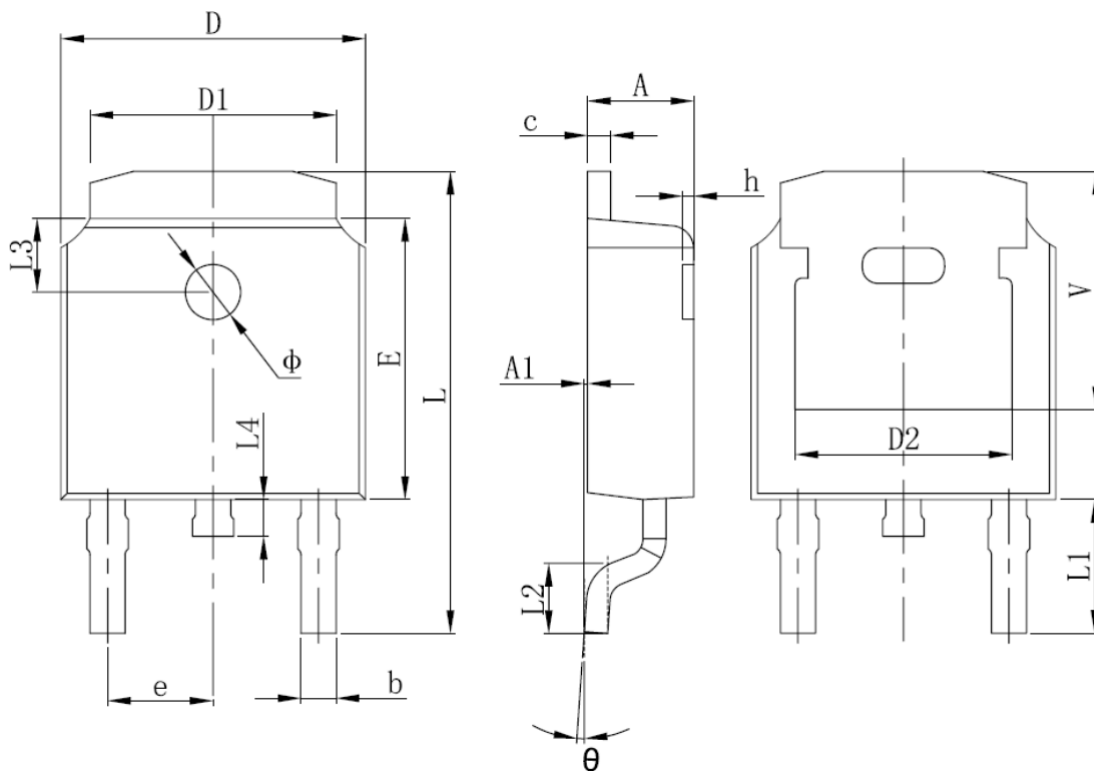


Gate-Source Voltage vs. Gate charge



Safe Operating Area vs. Junction-to-Ambient

➤ Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 |
| b | 0.635 | 0.770 | 0.025 | 0.030 |
| c | 0.460 | 0.580 | 0.018 | 0.023 |
| D | 6.500 | 6.700 | 0.256 | 0.264 |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 |
| D2 | 4.830 REF. | | 0.190 REF. | |
| E | 6.000 | 6.200 | 0.236 | 0.244 |
| e | 2.186 | 2.386 | 0.086 | 0.094 |
| L | 9.712 | 10.312 | 0.382 | 0.406 |
| L1 | 2.900 REF. | | 0.114 REF. | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 |
| L3 | 1.600 REF. | | 0.063 REF. | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 |
| Φ | 1.100 | 1.300 | 0.043 | 0.051 |
| θ | 0° | 8° | 0° | 8° |
| h | 0.000 | 0.300 | 0.000 | 0.012 |
| V | 5.250 REF. | | 0.207 REF. | |



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